

REMARKS/ARGUMENTS

**1. Rejection of claims 7-9 under 35 U.S.C. 102(e) as being anticipated by Chase et al.
(US 2005/0227400):**

5 Claim 7:

Claim 7 is currently amended to include the limitation “the first surface of the wafer is bonded to a carrier with a bonding layer while removing the wafer in the two through regions” of dependent claim 10 as suggested by the Examiner in regards to allowable subject matter. Therefore, applicant believes that amended claim 7 has
10 been placed in condition for allowance. Reconsideration of currently amended independent claim 7 is respectfully requested.

Claims 8-9:

Claims 8-9 are dependent on claim 7, and should be allowed if claim 7 is found
15 allowable. Reconsideration of claims 8-9 is therefore requested.

2. Allowable subject matter:

Claims 10-11:

20 The limitation of claim 10 has been amended to claim 7, and claim 10 has been cancelled. Claim 11 is dependent on claim 7, and should be allowed if claim 7 is found allowable. Reconsideration of claim 11 is therefore requested

Claims 1-6:

25 Claims 1-6 are allowed.

Applicant respectfully requests that a timely Notice of Allowance be issued in this

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case.

Sincerely yours,

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Date: 01/23/2007

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